



**Microbonds**

## **MARCH PLASMA SYSTEMS AND MICROBONDS FORM TECHNICAL ALLIANCE**

**Concord, CA. & Toronto, ON.,** (June 29, 2006) -- March Plasma Systems, Inc. a Nordson Corporation company (NASDAQ: NDSN) and Microbonds Inc. (a private Canadian corporation) today announced a co-development project to align the technology roadmaps of Microbonds' insulated wire bonding technology, X-Wire™ Technology, with the March Plasma Systems line of automated and batch plasma treatment systems.

Microbonds' X-Wire Technology enables bonding wires connecting the die to the substrate to touch without causing an electrical short, facilitating the adoption of fine diameter bonding wires, longer bonding wires, area array bonding, higher density stacked die, multi-tier and other 3-D packages, as well as an array of new packaging designs.

March Plasma Systems is the global leader in plasma processing technology for the Semiconductor industry, specifically wafer level and advanced packaging applications. The company designs and manufactures advanced plasma treatment systems, and maintains an expert staff of scientists and engineers trained in plasma science for advanced packaging technology.

"Microbonds' X-Wire Technology is an innovative solution to some of the pressing interconnect packaging and yield challenges facing many of our customers, and we are eager to support the evolution of a robust and cost effective insulated bonding wire solution", said Peter Bierhuis, President of March Plasma Systems.

"Plasma treatment is commonly used in the packaging process to improve bond strength and increase device yield and reliability. Ensuring compatibility of our insulating technology with all aspects of the assembly process is a key component in our commercialization efforts " stated John Scott, CEO of Microbonds Inc. "The expert technical capabilities of the March Plasma Systems team has been instrumental in helping us develop compatible process windows that will meet the requirements of our common customers" he continued.

### **About March Plasma Systems**

March Plasma Systems is the global leader in plasma processing technology for the semiconductor, PCB, and microelectronics industries. March has operations, applications laboratories, and customer support centers worldwide, including California, Florida, Europe, Singapore, China, Japan, Korea and Taiwan. With over 20 years of continuous innovation, March designs and manufactures a complete line of award-winning and patented plasma processing systems. An expert staff of scientists and engineers is available to assist in the design of plasma processes that improve both product reliability and increase production yields. Contact March Plasma Systems directly or see the March web site for more details:

For more information, see [www.marchplasma.com](http://www.marchplasma.com)

### **About Microbonds:**

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. The company's X-Wire™ Technology has recently received a Technology Innovation Award from SEMI®.

For more information, see [www.microbonds.com](http://www.microbonds.com)

March®, a Nordson Company, is a registered trademark of Nordson Corporation. Microbonds and X-Wire Technology are trademarks of Microbonds, Inc. All other trademarks and registered trademarks are the property of their respective owners.

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